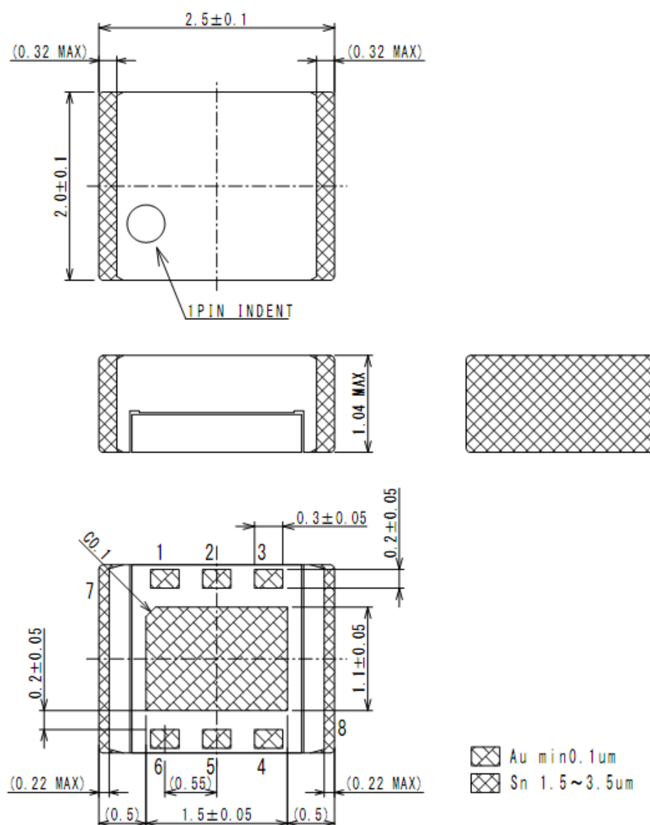
外形寸法図 Packaging Information / 参考パターン寸法 Reference Pattern Layout Dimensions

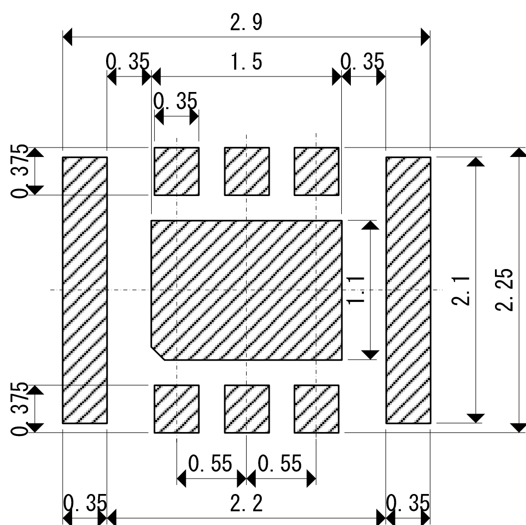
CL-2025-02

Unit : inch (mm)

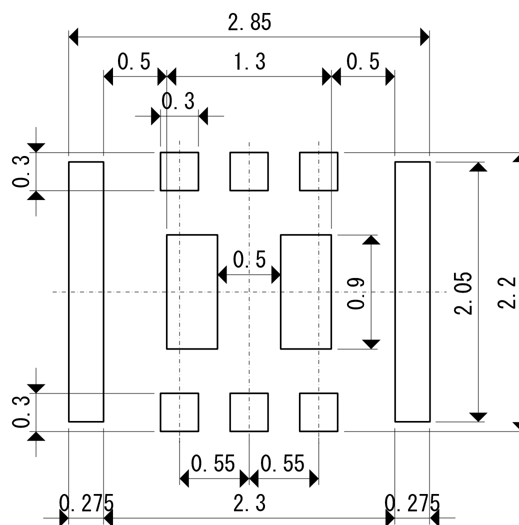
●外形寸法図 / Packaging Information



●参考パターン寸法/ Reference Pattern Layout



●参考メタルマスクデザイン / Reference metal mask design

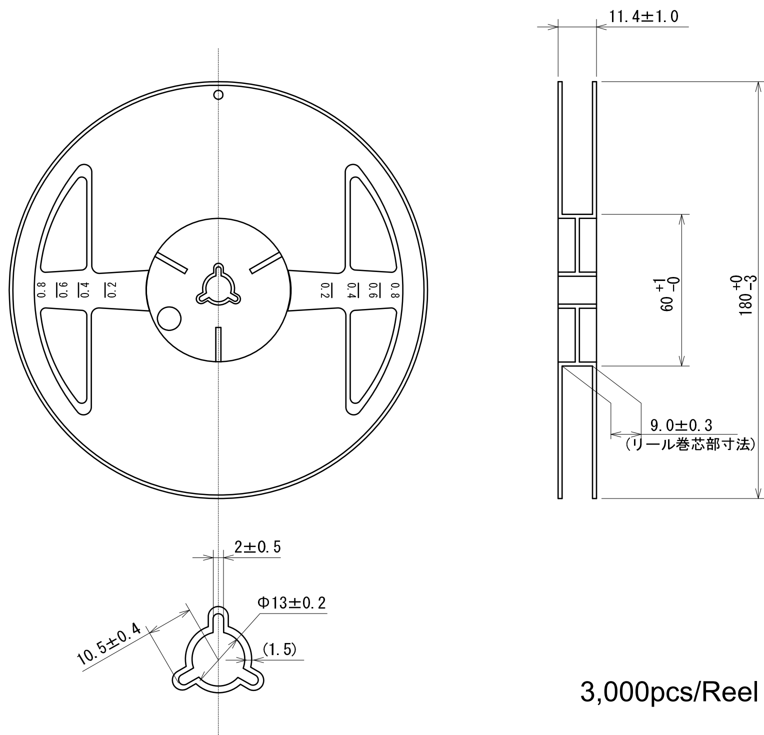


*CL-2025-02 の実装は精度 0.05mm 以内を推奨します。

テーピング仕様 / Taping Specifications

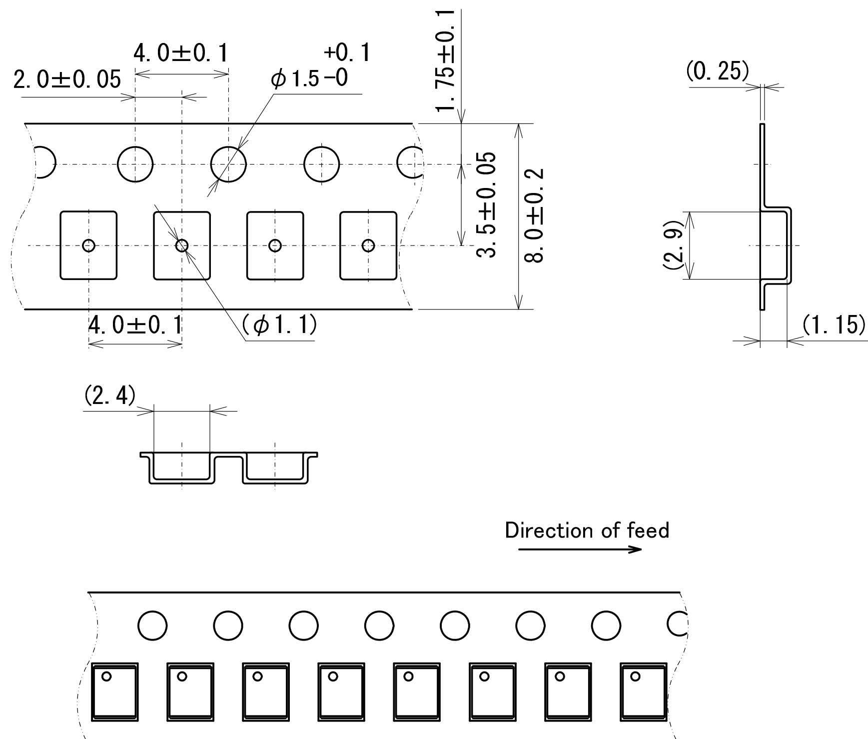
CL-2025-02

●リール/Reel



3,000pcs/Reel

●テーピング仕様/Taping Specifications



● CL-2025-02 Power Dissipation

Power dissipation data for the QFN-24 is shown in this page.

The value of power dissipation varies with the mount board conditions.

Please use this data as one of reference data taken in the described condition.

1. Measurement Condition (Reference data)

Condition: Mount on a board

Ambient: Natural convection

Soldering: Lead (Pb) free

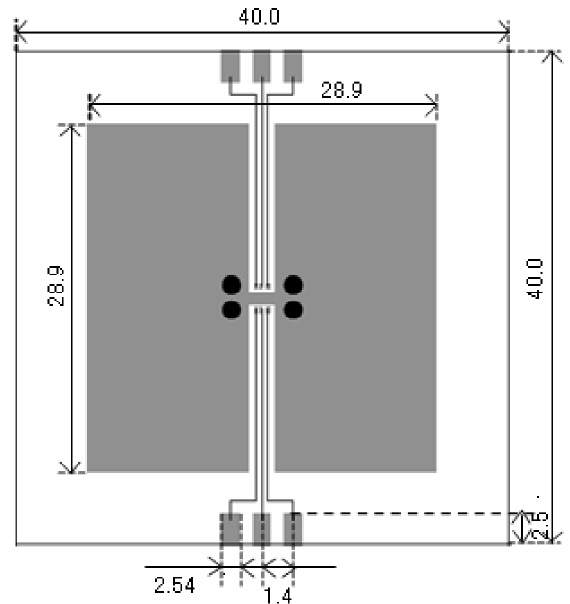
Board Dimensions: 40 x 40 mm ($1600mm^2$ in one side)

Copper (Cu) traces occupy 50% of the board area In top and back faces Package heat-sink is tied to the copper traces

Material: Glass Epoxy (FR-4)

Thickness: 1.6 mm

Through-hole: 4 x 0.8 Diameter



Evaluation Board (Unit:mm)

2. Power Dissipation vs. Ambient Temperature

Board Mount (Tjmax=125℃)

Ambient Temperature (℃)	Power Dissipation Pd (mW)	Thermal Resistance (℃/W)
25	1000	100.00
85	400